

## CLAIMS

What is claimed is:

1. A method of transferring semiconductor chips from a substantially flat wafer having an active side with a plurality of individual semiconductor chips formed thereon and a support side opposite said active side to a receiver, said method comprising the steps of: supporting the wafer with its support side attached by way of an adhesive sheet to a support structure, cutting the wafer into segments corresponding to said individual semiconductor chips so that said semiconductor chips are individually supported on said adhesive sheet with their active sides exposed and facing away from said adhesive sheet, moving said support structure with said individual semiconductor chips into a position wherein a particular semiconductor chip to be removed is positioned in a removal location above a receiver location, and pushing the adhesive sheet at the particular semiconductor chip location downwardly so as to release said particular semiconductor chip and transfer it with the active side thereof onto said receiver.

2. A method according to claim 1, wherein said receiver is a transport device, whereby said semiconductor is moved to a transfer location for being picked up by a handling device.

3. A method according to claim 2, wherein said individual semiconductor chip is picked up by said handling device with the exposed active surface thereof facing downwardly for deposit in the same orientation in a housing of for installation on a printed circuit board.

4. A method according to claim 2, wherein said individual semiconductor chip is moved from said removal location to said transfer location in a plane extending parallel to said wafer.